

WE CLAIM:

1. A circuit board comprising:
an insulator plate;
a first conductor layer provided on one surface of the insulator plate;
a second conductor layer provided in a position facing to the first conductor layer on the insulator plate; and
a conductor electrically connected to the first conductor layer and the second conductor layer.
2. A circuit board according to claim 1, which comprises a dielectric interposed between said first conductor layer and said second conductor layer.
3. A circuit board according to claim 1, wherein a position of an end portion of said second conductor layer is at a position of an end portion of said first conductor layer or at a position between the end portion of said first conductor layer and an end portion of said insulator plate.
4. A circuit board according to claim 1, wherein said second conductor layer comprises a layer selected from the group consisting of a metallized layer of tungsten, a metallized layer of molybdenum and manganese, a layer plated over a metallized layer of tungsten, and a layer plated over a metallized layer of molybdenum and manganese.

5. A circuit board comprising:
 an insulator plate;
 a first conductor layer provided on one surface of the insulator plate;
 a second conductor layer separated from the conductor layer on the insulator plate; and
 a conductor electrically connected to the first conductor layer and the second conductor layer.

6. A circuit board comprising:
 an insulator plate;
 a conductor layer placed on a surface of the insulator plate;
 a dielectric layer provided in a gap portion between the insulator plate and the conductor layer wherein:
 the following relationship exists among the dielectric constant of the dielectric layer ϵ_g , the dielectric constant of the insulator plate ϵ_b , the thickness of the gap portion L_g , and the thickness of the insulator plate L_b ,

$$\epsilon_g \geq \epsilon_b \times (L_g/L_b).$$